

# Errata to the MPC855T User's Manual, Rev. 1

This errata document describes corrections to the *MPC855T User's Manual*, Revision 1. For convenience, the section number and page number of the errata item in the reference manual are provided. Items with section and page numbers in bold are new since the last revision of this document.

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<b>Section/Page</b>	<b>Changes</b>
12, 12-3	On the top right side of Figure 12-2, replace 'F4-VDDH' with 'F4-VDDL.' Remove 'T14' from the list.
12.5, 12-28	In the second row of Table 12-5, add a footnote at end of sentence that states: At power-on reset, port pin states are not defined in any particular state until CLKOUT is present for two clocks.
<b>15.6.4.7, 15-49</b>	In Table 15-19, "AMA/AMB Definition for DRAM Interface)," add a footnote to "Memory Size" that states the following: "Memory Size takes data bus width into account."
21.2.1, 21-9	In the MODE field (bits 28–31) of Table 21-2, V.14 RAM microcode is not supported. Thereby, mode 0111 should be 'Reserved.'
21.2.1, 21-9	In the MODE field (bits 28–31) of Table 21-2, DDCMP RAM microcode is not supported. Thereby, mode 1001 should be 'Reserved.'
<b>21.2.4, 21-10</b>	In Table 21-3, "TODR Field Descriptions," in TOD field description, change "TOD is cleared automatically after one serial clock..." to say "TOD is cleared automatically after 1 system clock..."

Section, Page No.	Changes
<b>21.2.4, 21-10–21-11</b>	In Figure 21-5, change the TODR register access from R/W to W (write only). Also, in Table 21-3, revise the second sentence of bit setting 1 in the TODR[TOD] description to read “TOD is cleared automatically after one system clock cycle, but...”
<b>21.3, 21-12</b>	Under third bullet point, change “For an RxBD, the value must be even,” to say, “For an RxBD, the value must be mod 4 aligned.”
<b>22, 22-1</b>	The last sentence in the last paragraph should be removed.
<b>22.16, 22-14</b>	In the RZS field (bit 7) of Table 22-9, for selection 1, the second sentence in the paragraph (making reference to V.14 applications) should be removed.
27.8, 27-13	Add superscript number 2 after PADDR1_H, PADDR1_M, and PADDR1_L.
27.8, 27-14	Add superscript number 2 after TADDR_H, TADDR_M and TADDR_L. Add a note 2 at the bottom of Table 27-1 with the statement:  The address should be written in little endian, not Motorola’s big-endian format (that is, physical address 112233445566 should be written PADDR_L = 6655, PADDR_M = 4433, and PADDR_H = 2211. The TADDR should be written in the same way as the PADDR).
27.22, 27-28	Change the last sentence in step 26 to read, “Then write 0x000E to TxBD[Data... .”
<b>30.4.1.2, 30-9</b>	In the last sentence of example 1, change the order of the string for REV = 1 to the following:  first            j_klmn__r_stuv    last
30.4.1.2, 30-10	In the last sentence of example 3, change the order of the string for REV = 1 to the following:  first            r_stuv_ghij_klmn    last
31.4.3, 31-8	Table 31-3, replace the text in the description with the following:  Division ratio 0–7. Specifies the divide ratio of the BRG divider in the I <sup>2</sup> C clock generator. The output of the prescaler is divided by $2 \times (DIV + 3 + (2 \times FLT))$ , and the clock has a 50% duty cycle. The FLT bit is in the I2MOD register. The minimum value for DIV is 3 if the digital filter is disabled (FLT = 0) and 6 if the digital filter is enabled (FLT = 1).
33.1, 33-2	Add a footnote reference number at the end of the statement of the sixth bullet with the following footnote:  At power-on reset, port pin states are not defined in any particular state until CLKOUT is present for two clocks.
43.2.12, 43-10	Change the term ‘60x’ in the first and fourth sentences to ‘external.’
<b>B.3.1, B-4</b>	In Table B-1, the row making reference to SCC in Profibus should be removed.

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